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(54) Title: LASER ABLATION APPLICATIONS FOR ELECTROSTATIC CHUCKS

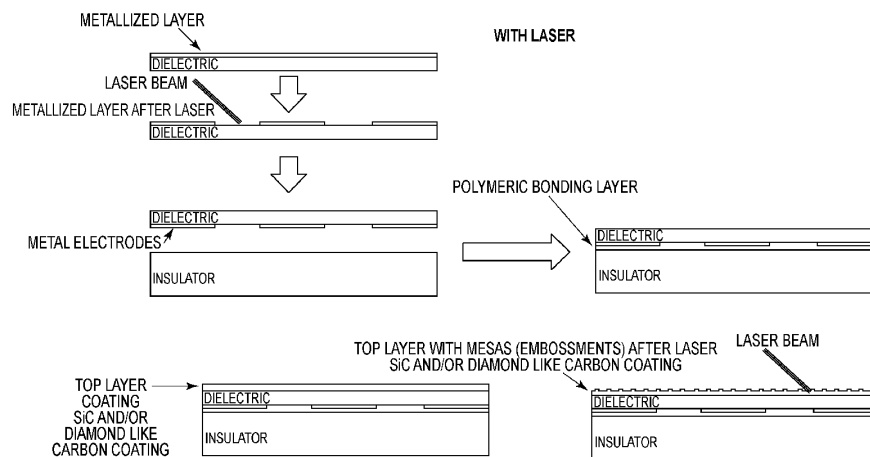


FIG. 2

(57) Abstract: Electrostatic chucks and methods for forming electrostatic chucks are provided. A method comprises obtaining a substrate comprising an etch resistant coating layer; ablating, with a laser, the etch resistant coating layer so as to remove at least a portion of the etch resistant coating layer so as to provide one or more exposed portions of the substrate; and forming an electrostatic chuck, wherein, when measuring an electrical resistance across the one or more exposed portions of the substrate between two metallized portions, the electrostatic chuck exhibits an electrical isolation of 300 GΩ or more. An electrostatic chuck comprises a substrate having at least one etch resistant coating layer comprising a laser ablated pattern, wherein the laser ablated pattern comprises one or more exposed portions of the substrate spanning distances of at least 0.5 mm.

[Continued on next page]

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